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Our File: MIT 10523

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Lee et al. **GROUP:** 2871
SERIAL NO: 10/043,896 **EXAMINER:** G.Y. Wang
FILED: January 9, 2002
FOR: HIGH DENSITY INTEGRATED OPTICAL CHIP

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

RESPONSE

In response to the Office Action mailed November 19, 2003, please amend the above-identified application as follows: